

HIGH-SPEED LOW-PROFILE OPEN-PIN-FIELD

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?LPAM

Insulator Material:

Black LCP

Terminal Material:

Copper Alloy

Plating:

Au or Sn over 50 μ" (1.27 μm) Ni

Current Rating:

2.2 A per pin (6 adjacent pins powered)

Working Voltage:

250 VAC

RoHS Compliant:

Yes

Lead-Free Solderable:

Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



Mates with:

LPAF

Standoffs:

JSO, SO

POWER/SIGNAL APPLICATION



Compatible with UMPT/UMPS for flexible two-piece power/signal solutions

Up to 40 pins per row

4, 6 or 8 row standard
.050" (1.27 mm) X
.050" (1.27 mm) pitch

Dual Blade terminal

Solder crimp

4 mm, 4.5 mm and 5 mm stack heights

HIGH-SPEED CHANNEL PERFORMANCE

LPAM/LPAF @ 5 mm Mated Stack Height
Rating based on Samtec reference channel.
For full SI performance data visit Samtec.com or contact SIG@samtec.com

PAM 4

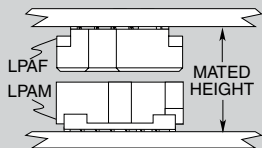
56 Gbps

ALSO AVAILABLE (MOQ Required)

- Tin-Lead Solder Charge
 - Other pins/row and row counts
 - Other Gold plating options
- Contact Samtec.

| | | | | | | | |
|-------------|------------------------------|--------------------------------------------------|---------------------------------------------------------------------|-------------------------------------------------------|-----------------------------|--------------------------------------|-------------------|
| LPAM | NO. PINS PER ROW | LEAD STYLE | PLATING OPTION | NO. OF ROWS | SOLDER TYPE | K | TR |
| | -10, -20, -30, -40 (Per Row) | -01.0 = (1.0 mm) .039" -01.5 = (1.5 mm) .060" | -L = 10 μ" (0.25 μm) Gold on contact area, Matte Tin on solder tail | -04 = Four Rows -06 = Six Rows -08 = Eight Rows | -2 = Lead-Free Solder Crimp | -K = Polyimide film Pick & Place Pad | -TR = Tape & Reel |

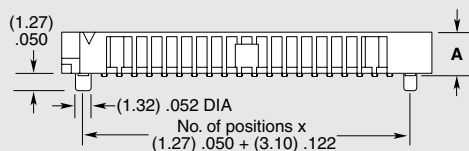
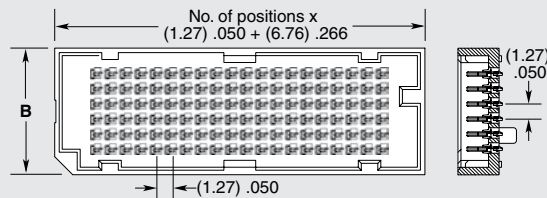
MATED HEIGHT



| NO. OF ROWS | B |
|-------------|--------------|
| -04 | (8.18) .322 |
| -06 | (10.72) .422 |
| -08 | (13.26) .522 |

| MATED HEIGHT* | | |
|-----------------|-----------------|-------------|
| LPAM LEAD STYLE | LPAF LEAD STYLE | |
| | -03.0 | -03.5 |
| -01.0 | (4.00) .157 | (4.50) .177 |
| -01.5 | (4.50) .177 | (5.00) .197 |

*Processing conditions will affect mated height.



| LEAD STYLE | A |
|------------|-------------|
| -01.0 | (3.68) .145 |
| -01.5 | (4.19) .165 |

Notes:

Patent Pending

Some sizes, styles and options are non-standard, non-returnable.

Due to technical progress, all designs, specifications and components are subject to change without notice.

WWW.SAMTEC.COM

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.